



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Hideyuki Kurita et al.

Group Art Unit: 2827

Application No.: 09/640,862

Examiner: I. Patel

Filed: August 18, 2000

Docket No.: 107082

For: PROCESSES FOR MANUFACTURING FLEXIBLE WIRING BOARD AND THE
RESULTING FLEXIBLE WIRING BOARD

SUPPLEMENTAL AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

Further to the April 18 personal interview with Examiner Patel and Primary Examiner Cuneo and the April 24 telephone interview with Examiner Patel, and as a supplement to the Amendment filed on April 2, 2003, please further amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claim 14 as follows:

14. (Three Times Amended) A flexible wiring board comprising a plurality of patterned metal films with a resin film being interposed therebetween, among which at least adjacent two patterned metal films are electrically connected to each other via bumps, one of said patterned metal film having at least one opening, wherein said resin film includes a solvent and the resin film is thermally shrinkable to press said bumps against said at least adjacent two patterned metal films by discharging the solvent through at least one opening of said patterned metal film when heat is applied to the flexible wiring board.